

**MECHATRONICS****Call for Papers****Focused Section on Sensing Technologies for Biomechatronics**

Recent advances in sensing technology have produced exciting new ideas in the growing field of biomechatronic devices. The successful integration of such devices requires thorough understanding of not only mechanical and electrical components, but also related physiology, biology, and neuroscience. This Focused Section of the IEEE/ASME Transactions on Mechatronics (TMECH) is dedicated to the new advances in modeling, design, fabrication, analysis, implementation, and validation of such sensors and related technologies for biomedical applications. Multidisciplinary papers are encouraged to submit. Potential topics include but are not limited to:

- Novel sensing principles
- Novel calibration techniques
- Biologically inspired sensors
- Sensors for biomedical applications (rehabilitation, healthcare monitoring, etc)
- In-vivo measurement of cells
- Measurement of bio-signals (EMG, EEG, MEG, etc)
- Wearable sensors
- Motion capturing
- Ultrasonic imaging
- MRI/fMRI compatible sensors
- Stereo or multiple vision systems
- Chemical sensors
- MEMS sensors

**Manuscript Submission**

Please submit the manuscripts in PDF format to <http://mc.manuscriptcentral.com/tmech-ieee/>, and indicate on your cover letter that “*This paper is submitted for possible publication in the Focused Section on Sensing Technologies for Biomechatronics.*” Instructions for authors are available online at: <http://www.ieee-asme-mechatronics.org>. The papers should contain both the theoretical and practical/experimental results and are subject to the TMECH review procedures. If you have any questions relating to this Focused Section, please email one of the guest editors.

<b>Important Dates:</b>	November 1, 2010	Paper Submission
	February 1, 2011	Completion of First Review
	March 15, 2011	Submission of Revised Paper
	June 1, 2011	Completion of Final Review
	July 1, 2011	Submission of Final Manuscripts and Copyright Forms
	October 2011	Publication

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